



BSI Standards Publication

Device embedded substrate

Part 2-1: Guidelines — General description
of technology

National foreword

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TECHNICAL SPECIFICATION

SPECIFICATION TECHNIQUE



**Device embedded substrate –
Part 2-1: Guidelines – General description of technology**

**Substrat avec appareil(s) intégré(s) –
Partie 2-1: Directives – Description générale de la technologie**

INTERNATIONAL
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CONTENTS

FOREWORD.....4

INTRODUCTION.....6

1 Scope.....7

2 Normative references.....7

3 Terms, definitions and abbreviations7

 3.1 Terms and definitions7

 3.2 Abbreviations7

4 Technology of device embedded substrate.....7

 4.1 Basic structures7

 4.2 Technology of device embedded substrate9

 4.3 Structures of device embedded substrates and terms used in this specification12

5 Jisso mounting and interconnection.....13

 5.1 General.....13

 5.2 Interconnections and structures of device embedded substrate15

 5.3 Device embedding by conventional process17

 5.4 Device embedding using vias19

6 Naming of each section22

 6.1 General.....22

 6.2 General definition of top and bottom surfaces22

 6.3 Naming of layers and interconnection position24

 6.4 Definitions of insulation layer thickness, conductor gap and connection distance between terminal and conductor27

 6.4.1 General27

 6.4.2 Insulation layer thickness, conductor gap and electrode/conductor gap in pad connection27

 6.4.3 Insulation layer thickness, conductor gap and electrode/conductor gap in a via connection28

 6.5 Additional information28

 6.5.1 Additional information for the insulation layer28

 6.5.2 Additional information for conductor gap and electrode/conductor gap29

Bibliography30

Figure 1 – Examples of device embedded substrate8

Figure 2 - Completed device embedded substrate (pad connection)9

Figure 3 - Completed device embedded substrate (via connection)9

Figure 4 – Structure of a pad connection type substrate on a passive device embedded ceramics base10

Figure 5 – Structure of a device embedded substrate using a ceramic board as the base (via connection type).....10

Figure 6 – Entire structure of device embedded substrate.....15

Figure 7 – Base (typical structure).....16

Figure 8 – Base (cavity structure).....16

Figure 9 – Base (insulator).....16

Figure 10 – Base (Conductive carrier – metal plate).....	16
Figure 11 – Passive device embedded ceramic board used as a base.....	17
Figure 12 – Ceramic board used as base (ceramic)	17
Figure 13 – Wire bonding connection and embedding of active device bare die	17
Figure 14 – Soldering connection and embedding of active device	18
Figure 15 – Soldering connection of square type passive device	18
Figure 16 – Conductive resin connection and embedding of active device	18
Figure 17 – Conductive resin connection and embedding of square type passive device.....	19
Figure 18 – Soldering connection into through hole and embedding of passive device	19
Figure 19 – Connection by copper plating after embedding of active device	19
Figure 20 – Connection by copper plating after embedding of square type passive device	20
Figure 21 – Conductive paste connection after embedding of active device package	20
Figure 22 – Conductive paste connection after embedding of square type passive device chip 20	20
Figure 23 – Device embedded substrate for device embedding in multi layers	21
Figure 24 – Embedding of devices over multiple layers	21
Figure 25 – Resin base substrate	21
Figure 26 – Conductor and metal sheet/copper foil as base substrate	22
Figure 27 – Device embedded substrate using passive device embedded ceramic substrates as base substrate – Second type.....	22
Figure 28 – Definition of top and bottom surfaces	23
Figure 29 – Definition of top and bottom surfaces (mounting of a mother board).....	23
Figure 30 – Names of layers in pad connection.....	24
Figure 31 – Additional information concerning the interconnection position	25
Figure 32 – Names of layers in via connection [I].....	25
Figure 33 – Names of layers in via connection [II].....	26
Figure 34 – Names of layers in via connection [III].....	26
Figure 35 – Definition of insulating layer thickness and conductor gap in pad connection 28	28
Figure 36 – Definition of electrode gap in via connection	28
Figure 37 – Additional illustration of insulating layer thickness	29
Figure 38 – Additional illustration for conductor gap and electrode/connector gap	29
Table 1 - Classification of device embedding	11
Table 2 – Formed embedded device into the substrate	12
Table 3 – Embedded device structure and fabrication process	13
Table 4 – Jisso mounting and interconnection of device embedded substrate.....	14
Table 5 – Names of layers of device embedded board	27

INTERNATIONAL ELECTROTECHNICAL COMMISSION

DEVICE EMBEDDED SUBSTRATE –**Part 2-1: Guidelines – General description of technology**

FOREWORD

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Technical Specifications are subject to review within three years of publication to decide whether they can be transformed into International Standards.

IEC TS 62878-2-1, which is a Technical Specification, has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this Technical Specification is based on the following documents:

Enquiry draft	Report on voting
91/1142/DTS	91/1163A/RVC

Full information on the voting for the approval of this Technical Specification can be found in the report on voting indicated in the above table.

A list of all parts in the IEC 62878 series, published under the general title *Device embedded substrate*, can be found on the IEC website.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

This part of IEC 62878 provides guidance with respect to device embedded substrate, fabricated by embedding discrete active and passive electronic devices into one or multiple inner layers of a substrate with electric connections by means of vias, conductor plating, conductive paste, and printing. Within the IEC 62878 series,

- IEC 62878-1-1 specifies the test methods,
- IEC TS 62878-2-1 gives a general description of the technology,
- IEC TS 62878-2-3 provides guidance on design, and
- IEC TS 62878-2-4 specifies the test element groups.

The device embedded substrate may be used as a substrate to mount SMDs to form electronic circuits, as conductor and insulator layers may be formed after embedding electronic devices.

The purpose of the IEC 62878 series is to achieve a common understanding with respect to structures, test methods, design and fabrication processes and the use of the device embedded substrate in industry.

DEVICE EMBEDDED SUBSTRATE – Part 2-1: Guidelines – General description of technology

1 Scope

This part of IEC 62878 describes the basics of device embedding substrate.

This part of IEC 62878 is applicable to device embedded substrates fabricated by use of organic base material, which include for example active or passive devices, discrete components formed in the fabrication process of electronic wiring board, and sheet formed components.

The IEC 62878 series neither applies to the re-distribution layer (RDL) nor to the electronic modules defined as an M-type business model in IEC 62421.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 61189 (all parts), *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*

3 Terms, definitions and abbreviations

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 apply.

3.2 Abbreviations

BGA	ball grid array
I/O	in/out
IPD	integrated passive device
LGA	land grid array
LTCC	low temperature co-fired ceramic
MEMS	micro electro mechanical systems
PoP	package on package
QFN	quad flat no-lead package
QFP	quad flat package
SMD	surface mount device
SOJ	small outline J-leaded package
WLP	wafer level package

4 Technology of device embedded substrate

4.1 Basic structures

Figure 1 shows an example of device embedding structures in the fabrication process of a device embedded substrate. Active and passive devices are connected to each other by interlayer vias and/or conductor patterns. Insulating layers are formed using insulating materials